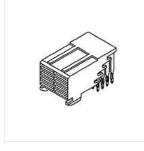


## RECTANGULAR POWER CONNECTORS



✓ Active



TE CONNECTIVITY (TE) 2MM FB,ASY,008,PWR,REC,EN,3.56 Z-PACK | RC Ƴ ⊡ f v

5536614-1 TE Internal Number: 5536614-1

## Always EU RoHS/ELV Compliant

Product Type **Connector Assembly** Housing Type **Receptacle** Applies To **Printed Circuit Board** Contact Current Rating (A) **3** Number of Positions **8** 

Product Drawings	Z-PACK 2mm FB, POWER MODULE, RCPT. ASS'Y. 4 ROW, 3.56mm LEAD LENGTH PRESS FIT LEAD PDF (TIFF AVAILABLE) English Z-PACK 2mm FB, POWER MODULE, RCPT. ASS'Y. 4 ROW, 3.56mm LEAD LENGTH PRESS FIT LEAD PDF (TIFF AVAILABLE) English
CAD Files	Customer View Model 2D_DXF.ZIP English 3D PDF PDF 3D
	Customer View Model 3D_IGS.ZIP English Customer View Model 3D_STP.ZIP English
Catalog Pages/Data Sheets	POWER_CONNECTORS_CATALOG_SEC01_BOARD_TO_BOARD PDF English

Please review product documents or **contact us** for the latest agency approval information. Please Note: Use the Product Drawing for all design activity.

Product Type Features

Product Type

Housing Type

**Connector Assembly** 

Receptacle

Contact Type

Socket

Certorium     2mml 0.791 h]       PCB Mounting Orientation     Ripkt Angle       Number of Rows     8       Number of Rows     2mml 0.791 h]       Row-to-Row Spacing     2mml 0.791 h]       Interface Type     Futurebuse       Contact Layout     Burley       eteriad Characteristics     Contact Current Rating (A)     3       contact Features     Contact Current Rating (A)     1000       contact Features     Contact Current Rating (A)     000       contact Features     Contact Termination Area Plating Material     Contact Current Rating (A)       contact Features     Contact Termination Area Plating Material     Gold       contact Termination Readmane (MO)     20     20       contact Termination Area Plating Material     Gold     2000       contact Termination Area Plating Thickness     27 µm [50 µm]       contact Termination Area Plating Thickness     127 µm [50 µm]       atmination Features     Contact Reamon     14.43       technical Attachment     PCB Mount Reamon     Sofder Tail (Pin)       causing Features     Height     Sofder Tail Contact Carlet Dependent       imensions     Height To     Prived Circuit Board       ipention/Application     Applies To     Sofder Tail Charlet Carlet Dependent       ipention/Application     Applies To	Configuration Features	Number of Positions	8	
Number of Power Positions     8       Number of Rows     4       Row-to-Row Spacing     2 mm[.079 in]       Interface Type     Futurebuse       Contact Lyout     8       betrial Characteristics     Contact Lyout       extrine Rating (A)     1       insulation Resistance (M2)     5000       entact Features     Contact Termination Area Plating Material     Gold       Contact Lyout     Contact Mating Area Plating Thickness (µm)     76       Contact Mating Area Plating Thickness (µm)     76       Contact Termination Area Plating Thickness (µm)     76       Contact Termination Area Plating Thickness (µm)     5000       envination Features     Termination Area Plating Thickness (µm)     5.56.365       Termination Post/Tail Length (in)     3.56.365     3.56.365       Termination Post/Tail Length (in)     3.56.365     3.56.365       Termination Post/Tail Length (in)     5.06 area     1.4.143       Resisting Features     RCB Mount Resention Type     Boss       PCB Mount Resention Type     Solder Tail (Pina)       Resisting Temperature     S.70 mm[.357 in]       Peaters     Height     Solder Tail Seard       Imperation/Application     Apples To     Prived Circuit Board       Operating Temperature     Sol Apples To     Sol Aspect Applicati	-			
Number of Rows4Row-to-Row Spacing2mm (.079 in )Interface TypePuturebuseContact LyoutNumber of RowsBectrical CharacteristicsContact Current Reling (A)Insulation Resistance (MG)3000ontact FeaturesContact Termination Area Flating MaterialContact Termination Area Flating MaterialTnContact Termination Area Flating MaterialContact Mating Area Plating Thickness (am)Contact Termination Area Flating Material76Contact Termination Area Flating Thickness (am)76Contact Termination Area Flating Thickness (am)76<		PCB Mounting Orientation		
Row-to-Row Spacing <b>zmm[.079 in]</b> Interface Type <b>Piturebus+</b> Contact Layout <b>Returebus+</b> Betchical CharacteristicsContact Current Rating (A) <b>3</b> contact FeaturesContact Current Rating (A) <b>5000</b> contact FeaturesContact Termination Area Plating MaterialTinContact Mating Area Plating MaterialContact Mating Area Plating MaterialContact Mating Area Plating Thickness (m)contact Base MaterialContact Mating Area Plating Thickness (m) <b>76</b> Contact Termination Area Plating Thickness (m) <b>79</b> contact Termination Area Plating Thickness (m) <b>5000</b> contact Termination Area Plating Thickness (m) <b>5000</b> contact Termination Area Plating Thickness (m) <b>5000</b> contact Current Alignment Type <b>Bose</b> PCB Mount Alignment Type <b>Bose</b> PCB Mount Retention <b>5016T Tail (Pin)</b> couting FeaturesHagitaumasionsHagitaperation/Application <b>50701 [Court Board</b> peration/Application <b>Printed Circuit Board</b> couting Temperature <b>5015T in]</b> couting Temperature <b>5015C ing Circuit 2007</b> peration/ApplicationPorteel Circuit Applicationperation/ApplicationPolesing Temperaturecouting Temperature <b>5015C ing Circ</b>		Number of Power Positions	8	
Interface Type Contact LayoutFuturebuse Matrixlectrical CharacteristicsContact Current Rating (A) Invalation Resistance (MC2)3ontact FeaturesContact Termination Area Plating Material Contact Mating Area Plating Material Contact Mating Area Plating Material Contact Rating Area Plating Thickness (III)Tmermination FeaturesContact Termination Area Plating ThicknessThrough Hole - Press-Fit 2.56, 3.65 2.605ermination FeaturesTermination Post/Tail Length (m) Termination Post/Tail Length (m)3.56, 3.65 3.64, 3.65 3.644technical AttachmentPCB Mount Retention PCB PCB PCB PCBPrinted Circuit Board Solder Tail (Pin)termination Poperature Corrating Temperature Corrating Temperature Corrating Temperature Corrating Temperature Corrating Temperature Corrating Temperature PCB PCBPrinted Circuit Board Solder Tail Corrat PCB PCBacaging FeaturesPackging MethodTube		Number of Rows	4	
Contact LayoutMatrixlectrical CharacteristicsContact Current Rating (A) Invalation Resistance (MC)3ontact FeaturesContact Termination Area Plating Material Contact Mating Area Plating Material Contact Mating Area Plating Material Contact Mating Area Plating Material Contact Base Material Contact Termination Area Plating ThicknessTmarmination FeaturesTermination Area Plating Thickness Contact Termination Area Plating ThicknessThrough Hole - Press-Fit 3.56, 3.65 1.27 µm [50 µm]armination FeaturesTermination Post/Tail Length (nm) Termination Post/Tail Length (nm) CEB Mount Retension PCB Mount Retension PCB Mount Retension TypeBoss Solder Tail (Pin)ousing FeaturesHousing Material Contact Retension TypeCP (Liquid Crystal Polymer)ousing FeaturesHeightSolder Tail (Pin) Solder Tail (Pin)areation ApplicationApplies To Operating Temperature Cruct ApplicationPrinted Circuit Board So 125 °C 1-67 - 257 °F) Poweracaging FeaturesPackajing MethodTube		Row-to-Row Spacing	2 mm [ .079 in ]	
lectrical Characteristics Contact Current Rating (A) Involution Resistance (M2) 5000 ontact Features Contact Termination Area Plating Material Contact Mating Area Plating Material Contact Mating Area Plating Material Contact Mating Area Plating Thickness (um) 74 Contact Mating Area Plating Thickness (um) 74 Contact Termination Post/Tail Length (um) 155		Interface Type	Futurebus+	
Insulation Resistance (M2) 5000 ontact Features Contact Termination Area Plating Material Gold Contact Mating Area Plating Thickness (an) 76 Contact Mating Area Plating Thickness (an) 76 Contact Base Material Plating Thickness 127 µm [50 µm] armination Features Termination Method to PC Board Through Hole - Press-Fit Termination Post/Tail Length (rm) 3.56, 3.65 Termination Post/Tail Length (rm) 14, 143 Rechanical Attachment PCB Mount Alignment Type Boss Rechanical Attachment PCB Mount Retention Type Solder Tail (Pin) couting Features Height Attachment PCB Mount Retention Type Solder Tail (Pin) couting Features Height PCB Mount Retention Type Solder Tail (Pin) couting Features Height PCB Mount Retention Type Solder Tail (Pin) couting Features PCB Mount Retention Type Solder Tail (Pin) couting Features Height PCB Mount Retention Type PCB Mount Retention Type Solder Tail (Pin) couting Features PCB Mount Retention Type Solder Tail (Pin) couting Features PCB Mount Retention Type PCB Mount Retention Type Solder Tail (Pin) couting Features PCB Mount Retention Type PCB Mount Retention Type PCB Mount Retention Type PCB Mount Retention Type Solder Tail (Pin) couting Features PCB Mount Retention Type PCB Power adaging Features PCB Mount Retention Type PCB Power circuit Application PCB Prime PCB Power		Contact Layout	Matrix	
antaet Features Contact Termination Area Plating Material Contact Mating Area Plating Material Gold Contact Mating Area Plating Material Contact Mating Area Plating Material Contact Mating Area Plating Material Phosphor Bronze Contact Termination Area Plating Thickness (µm) 76 Contact Base Material Contact Termination Area Plating Thickness 1.27 µm [50 µin] ermination Features Termination Method to PC Board Termination Post/Tail Length (rm) 3.56, 3.65 Termination Post/Tail Length (rm) 1.4, -143 techanical Attachment PCB Mount Alignment Type PCB Mount Retention Post/Tail Length (rm) Solder Tail (Pin) ousing Features Housing Material Housing Material PCB Mount Retention Type Solder Tail (Pin) termination Post/Tail Length (rm) 2.07 mm [.357 in] question/Application Housing Material Applies To Printed Circuit Board Operating Temperature Circuit Application Post/Tail Contact Application Post/Tail Contact Printed Circuit Board Printed Circuit Application Post/Tail Contact Printed Circuit Application Post/Tail Contact Printed Circuit Board Printed Circuit Application Post/Tail Contact Printed Circuit Board Printed Circuit Application Post/Tail Contact Printed Circuit Application Post/Tail Contact Printed Circuit Application Post/Tail Post Post Post Post Post Post Post Post	Electrical Characteristics	Contact Current Rating (A)	3	
Contact Mating Area Plating Material       Gold         Contact Mating Area Plating Thickness (µm)       .76         Contact Base Material       Phosphor Bronze         Contact Termination Area Plating Thickness       1.27 µm [50 µin]         armination Features       Termination Method to PC Board       Through Hole - Press-Fit         Termination Post/Tail Length (mm)       3.56, 3.65         Termination Post/Tail Length (in)       .14, .143         techanical Attachment       PCB Mount Alignment Type       Boss         PCB Mount Retention Type       Solder Tail (Pin)         cousing Features       Housing Material       LCP (Liquid Crystal Polymer)         imensions       Height       .907 mm [.357 in]         applies To       Printed Circuit Board       .55 - 125 °C [.47 - 257 °F]         Operating Temperature       .55 - 125 °C [.47 - 257 °F]       .55 - 125 °C [.47 - 257 °F]         actaging Features       Packaging Method       Tube		Insulation Resistance (M $\Omega$ )	5000	
Contact Mating Area Plating Thickness (µm)       76         Contact Base Material       Phosphor Bronze         Contact Termination Area Plating Thickness       127 µm [50 µm]         ormination Features       Termination Method to PC Board       Through Hole - Press-Fit         Termination Post/Tail Length (mm)       3.56, 3.65         Termination Post/Tail Length (mm)       14, 143         techanical Attachment       PCB Mount Alignment Type         PCB Mount Retention       With         PCB Mount Retention Type       Solder Tail (Pin)         ousing Features       Housing Material       Cortact Issue Material         urmensions       Height       9.07 mm [.357 in]         operation /Application       Applies To       Printed Circuit Board         Operating Temperature       So 5 - 125 °C [.47 - 257 °F]         Circuit Application       Power         acadaging Features       Pakaging Method       Tube	Contact Features	Contact Termination Area Plating Material	Tin	
Contact Base Material Contact Termination Area Plating ThicknessPhosphor Bronze 1.27 µm [50 µi]armination FeaturesTermination Method to PC Board Termination Post/Tail Length (m)Through Hole - Press-Fit 3.56, 3.65 1.4, 143techanical AttachmentPCB Mount Alignment Type PCB Mount Retention PCB Mount Retention TypeBoss With Solder Tail (Pin)ousing FeaturesHousing MaterialCP (Liquid Crystal Polymer)umensionsHeight9.07 mm [.357 in]aperation/ApplicationApplies To Operating Temperature Circuit ApplicationPristed Circuit Board - 55 - 125°C[-67 - 257°F] Powerackaging FeaturesPakaging MethodTube		Contact Mating Area Plating Material	Gold	
Contact Termination Area Plating Thickness1.27 µm [50 µin]armination FeaturesTermination Method to PC Board Termination Post/Tail Length (mm)Through Hole - Press-Fit 3.56, 3.65 14.143hechanical AttachmentPCB Mount Alignment Type PCB Mount Retention PCB Mount Retention TypeBoss Vith Solder Tail (Pin)ousing FeaturesHousing MaterialLCP (Liquid Crystal Polymer)imensionsHeight9.07 mm [.357 in]actaging FeaturesApplies To Operating Temperature Circuit ApplicationPrinted Circuit Board Poweractaging FeaturesPackaging MethodTube		Contact Mating Area Plating Thickness (µm)	.76	
ermination Features Termination Method to PC Board Through Hole - Press-Fit Termination Post/Tail Length (nm) 3.56, 3.65 Termination Post/Tail Length (in) .14, 143 techanical Attachment PCB Mount Alignment Type Boss PCB Mount Retention PCB Mount Retention PCB Mount Retention PCB Mount Retention Type Solder Tail (Pin) ousing Features Housing Material LCP (Liquid Crystal Polymer) timensions Height 9.07 mm [.357 in] Poperation/Application Applies To Printed Circuit Board Operating Temperature Coperating Temperature Power Circuit Application Packaging Method Tube		Contact Base Material	Phosphor Bronze	
Termination Post/Tail Length (mm)       3.56, 3.65         Termination Post/Tail Length (in)       .14, .143         techanical Attachment       PCB Mount Alignment Type       Boss         PCB Mount Retention       With         PCB Mount Retention       With         PCB Mount Retention Type       Solder Tail (Pin)         ousing Features       Housing Material       LCP (Liquid Crystal Polymer)         imensions       Height       9.07 mm [.357 in]         operation/Application       Applies To       Printed Circuit Board         Operating Temperature       -55 - 125 °C [-67 - 257 °F ]         Circuit Application       Pokaging Method       Tube		Contact Termination Area Plating Thickness	1.27 μm [ 50 μin ]	
Itermination Post/Tail Length (in).14143Itechanical AttachmentPCB Mount Alignment TypeBossPCB Mount RetentionWithPCB Mount Retention TypeSolder Tail (Pin)ousing FeaturesHousing MaterialLCP (Liquid Crystal Polymer)imensionsHeight9.07 mm [.357 in]operation/ApplicationApplies To Operating Temperature Circuit ApplicationPrinted Circuit Board -55 - 125 °C [-67 - 257 °F] Powerackaging FeaturesPackaging MethodTube	Termination Features	Termination Method to PC Board	Through Hole - Press-Fit	
Inchanical Attachment       PCB Mount Alignment Type       Boss         PCB Mount Retention       With         PCB Mount Retention Type       Solder Tail (Pin)         ousing Features       Housing Material       LCP (Liquid Crystal Polymer)         imensions       Height       9.07 mm [.357 in]         operation/Application       Applies To       Printed Circuit Board         Operating Temperature       -55 - 125 °C [.67 - 257 °F ]         Circuit Application       Power         ackaging Features       Packaging Method		Termination Post/Tail Length (mm)	3.56, 3.65	
PCB Mount Retention     With       PCB Mount Retention Type     Solder Tail (Pin)       ousing Features     Housing Material     LCP (Liquid Crystal Polymer)       imensions     Height     9.07 mm [.357 in]       operation/Application     Applies To     Printed Circuit Board       Operating Temperature     -55 - 125 °C [-67 - 257 °F]       Circuit Application     Power       ackaging Features     Packaging Method		Termination Post/Tail Length (in)	.14, .143	
PCB Mount Retention TypeSolder Tail (Pin)ousing FeaturesHousing MaterialLCP (Liquid Crystal Polymer)imensionsHeight9.07 mm [.357 in ]opperation/ApplicationApplies ToPrinted Circuit BoardOperating Temperature-55 – 125 °C [-67 – 257 °F ]Circuit ApplicationPower	Mechanical Attachment	PCB Mount Alignment Type	Boss	
ousing FeaturesHousing MaterialLCP (Liquid Crystal Polymer)imensionsHeight9.07 mm [.357 in]operation/ApplicationApplies ToPrinted Circuit BoardOperating Temperature-55 - 125 °C [-67 - 257 °F]Circuit ApplicationPower		PCB Mount Retention	With	
imensionsHeight9.07 mm [.357 in]operation/ApplicationApplies ToPrinted Circuit BoardOperating Temperature-55 - 125 °C [-67 - 257 °F]Circuit ApplicationPower		PCB Mount Retention Type	Solder Tail (Pin)	
Operation/Application     Applies To     Printed Circuit Board       Operating Temperature     -55 - 125 °C [-67 - 257 °F]       Circuit Application     Power       ackaging Features     Packaging Method	Housing Features	Housing Material	LCP (Liquid Crystal Polymer)	
Operating Temperature     -55 – 125 °C [-67 – 257 °F]       Circuit Application     Power       ackaging Features     Packaging Method     Tube	Dimensions	Height	9.07 mm [ .357 in ]	
Circuit Application     Power       ackaging Features     Packaging Method     Tube	Operation/Application	Applies To	Printed Circuit Board	
ackaging Features Packaging Method <b>Tube</b>		Operating Temperature	-55 – 125 °C [ -67 – 257 °F ]	
		Circuit Application	Power	
Packaging Quantity 48	Packaging Features	Packaging Method	Tube	
		Packadind Quantity	48	

Other	For Use With	Plug
Product Compliance	Statement of Compliance PDF	
	VIEW ALL PRODUCT COMPLIANCE	

## CUSTOMERS ALSO BOUGHT

RECTANGULAR POWER CONNECTORS	PCB D-SUB CONNECTORS	СХР	HARD METRIC BACKPLANE CONNECTORS
	•		
2MM FB, ASY, 008, PWR, HDR, EN, 4.25 5536603-1	09 RCPT SP/FMS (RET SL) 5750678-1	CXP RCPT KIT W/HEAT SINK 2149157-1	2MM HM ASY, T-B, HDR, 10R, 250, AP 5646357-1
Save to List  Find Similar Products	Save to List	Save to List	Save to List